



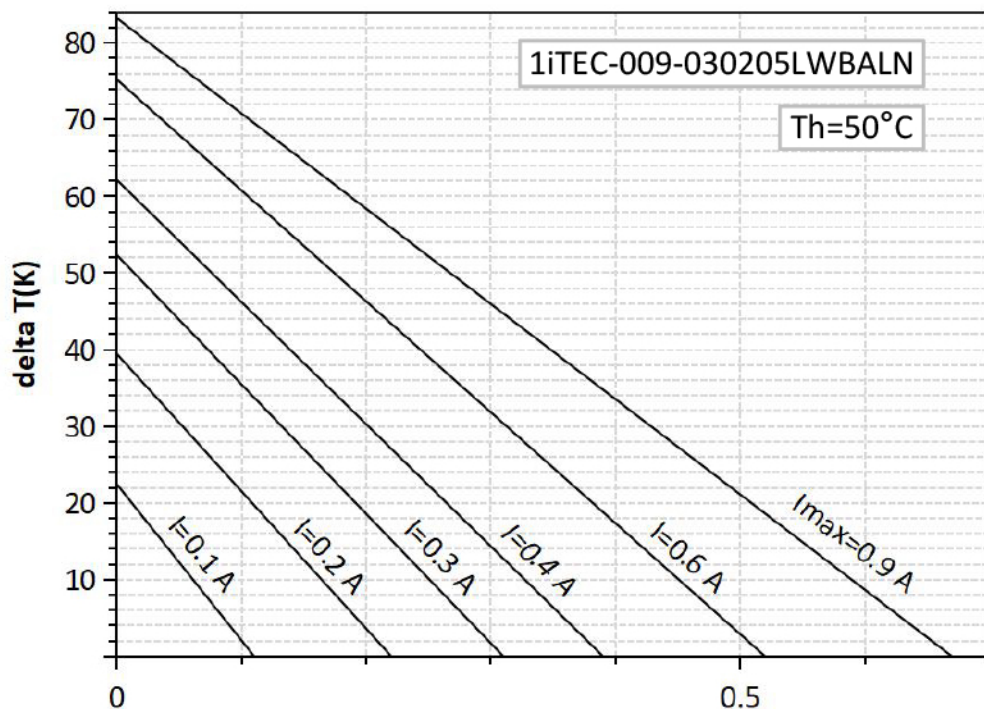
1iTEC-009-030205LWBALN

Maximum performance characteristics
($T_h=323\text{ K}$, vacuum)

$\Delta T_{\max}$ (K)	83.2
$Q_{\max}$ (W)	0.67
$I_{\max}$ (I)	0.9
$U_{\max}$ (V)	1.13
ACR (Ohm)	1.1 +/- 0.15

Parameter deviation: +/- 5%

TEC performance graph $Q_c=F(dT)$

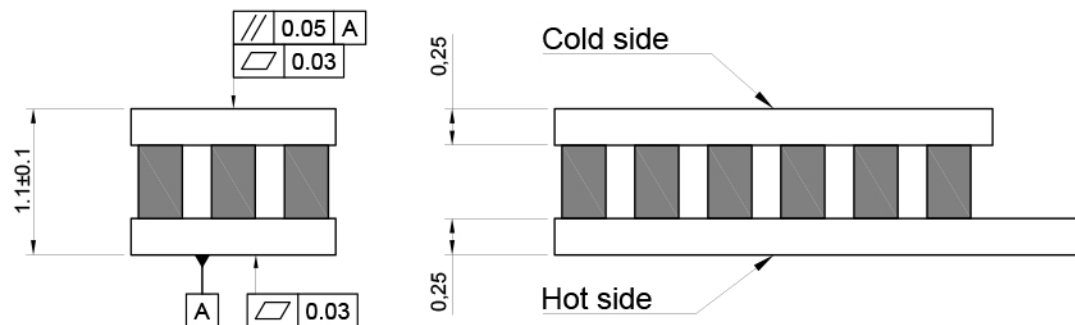


Notes:

Heat Load Q_c (W)

- all dimensions are in mm;
- maximum TEC processing temperature 200°C ;
- other performance graphs available on request;

Mechanical Characteristics



Manufacturing options

Inner solder SnBi (m.p. 230°C)

Ceramics 96 % AlN

TEC outer surfaces Cold Side - metallized, Au plated;

Hot Side - metallized, Au plated;

W.B. pads Areas destined for TEC lead wires. Ready for wire bonding process.

Product RoHS and REACH compliant;

